Dexerials

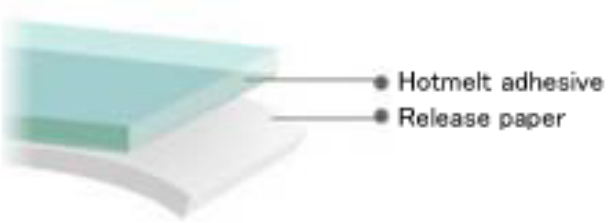
Technical Data Sheet

Polyester resin base hotmelt transfer tape D3600 series

Features

- Tack-free characteristics at room temperature allows spinning and direct-punching process without release liner, it effects good workability, and availability for various design feature.
- Well balanced adhesive performance effects excellent bonding strength for various kinds of substrate from plastics to metals from low temperature range.
- Excellent drop impact resistance allows it to be used for narrow bonding area.
- Spinning process after laminated to metal material is available, transfer type tape.

Structure

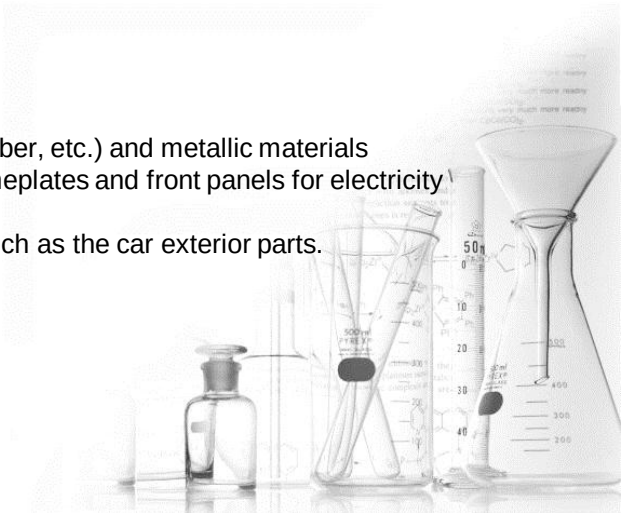


Products Name	D3600	D3620
Main component	Polyester base	Polyester base
Color	Translucent white	Translucent white
Adhesive thickness (μm)	about 50	about 200
Release paper thickness (μm)	about 130	about 130
Bonding strength (N／4c㎡) ※	2550	2649
St'd size (width & length)	510mm × 100m	480mm × 50m

※ Shear strength (Bonding at 150℃)

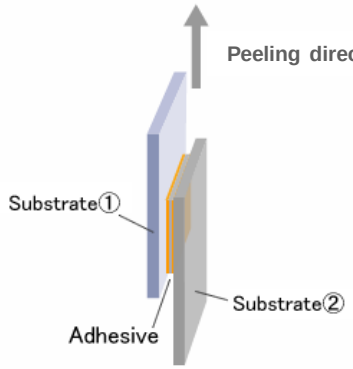
Suitable use

- Ideal for the bonding of plastic (ABS, PS, and acrylic fiber, etc.) and metallic materials (aluminum and stainless steel plate, etc.) such as nameplates and front panels for electricity and an electronic equipment.
- Ideal for the bonding of plastic and metallic material such as the car exterior parts.



Technical data

1. Bonding strength under different temperatures (Shear strength)



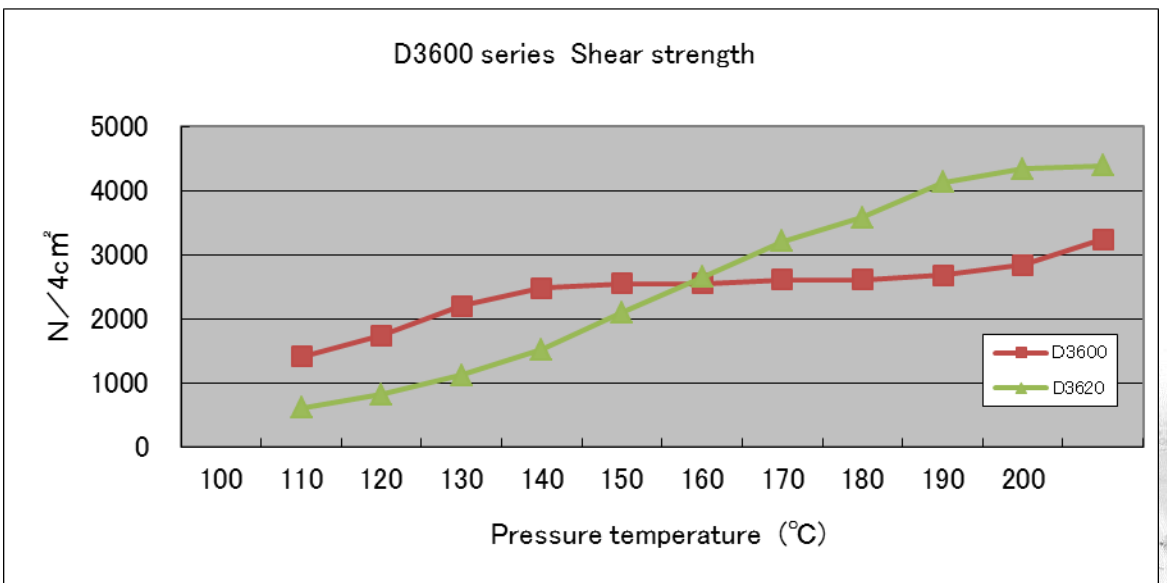
＜Shear strength test ＞

＜Test piece condition＞
Substrate① : SUS(0.5×25×100㎜)
Substrate② : PC･ABS(4.0×25×100㎜)
Bonding area : 20mm × 20mm
Bonding condition :
Pressure : 0.5MPa(5kgf/cm²)
Temperature : 100 to 200℃
Set time : 3 sec
Measuring condition : 23℃±5℃ 60%±20% RH
Peel speed : 20mm/min
［Left at RT for one day before measurement］

＜Results＞ (N/4cm²)

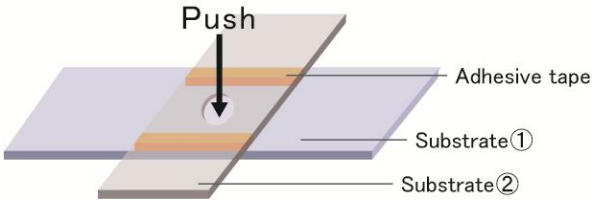
Pressure(℃) / Product	100	110	120	130	140	150
D3600	1407	1736	2197	2481	2545	2550
D3620	613	819	1118	1514	2098	2649

Pressure(℃) / Product	160	170	180	190	200
D3600	2609	2614	2677	2839	3242
D3620	3211	3575	4129	4335	4393



2. Bonding strength (Push test)

＜Test piece condition＞
Substrate① : SUS(1.0×50×100㎜)
Substrate② : PC･ABS(2.0×38×64㎜)
Bonding area : 2mm × 35mm / 2 pieces
Bonding condition :
Pressure : 0.5MPa(5kgf/cm²)
Temperature : 120 to 140℃
Set time : 3 sec
Measuring condition : 23℃±5℃ 60%±20% RH
Push speed : 10mm/min
［Left at RT for one day before measurement］



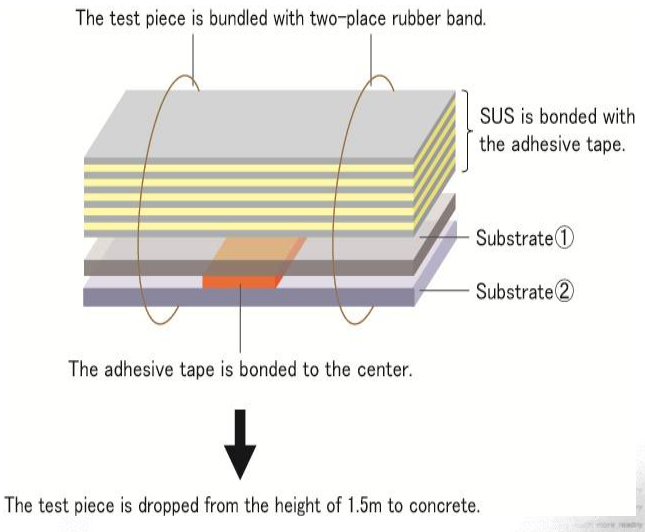
＜Bonding strength (Push test) ＞

＜Results＞ (N/ 1.4cm²)

Pressure temperature	D3600	D3620
120℃	39.2	426.7
130℃	73.6	＞500
140℃	250.2	＞500

3. Impact force resistance (Drop test)

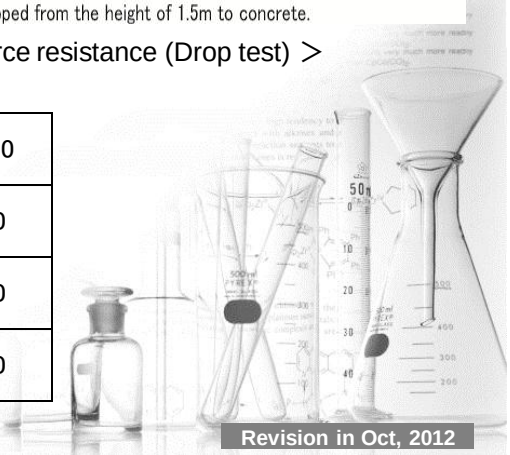
＜Test piece condition＞
Substrate① : SUS(1.0×50×100㎜)
Substrate② : PC･ABS(2.0×50×100㎜)
Bonding area : 10mm × 10mm
Bonding condition :
Pressure : 0.5MPa(5kgf/cm²)
Temperature : 120 to 140℃
Set time : 3 sec
Measuring condition : 23℃±5℃ 60%±20% RH
Height : 1.5m
Weight : 300g
The test piece is dropped to concrete.
Record the numbers when the test piece peel off.
［Left at RT for one day before measurement］



＜Impact force resistance (Drop test) ＞

＜Results＞

	Pressure temperature	D3600	D3620
Heigth:1.5m Weight:300g Bonding area:1cm² Record the numbers when the test piece peel off.	120℃	17	＞30
	130℃	26	＞30
	140℃	＞30	＞30



Revision in Oct, 2012

Note on the characteristic data given— Data on the characteristics of the products described in this catalog are based on the results of evaluations carried out by the company. This does not guarantee that the characteristics of the product conform with your usage environment. Before use, review the usage conditions based on evaluation data obtained from the equipment and substrates actually used.

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